

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A method of producing a printed circuit board mask for use in producing a resist pattern for etching of a printed circuit, comprising:

defining a desired pattern of conductor elements to be formed by etching away of conductive regions from a substrate carrying a conductive layer on its surface thereby to form the printed circuit;

defining a mask with reference to said desired pattern of conductor elements, the mask comprising masking elements for producing a resist pattern to be formed on the conductive layer on the substrate to leave exposed regions of said conductive layer to be etched away; and

defining in the mask a constant width etch band delineating individual conductor elements in the desired printed circuit conductor pattern.

2. (Original) A method according to claim 1 wherein the etch band is of substantially the same width as the narrowest conductor or the narrowest separation between conductors in the printed circuit.

3. (Original) A method according to claim 1 wherein the etch band separates the desired printed circuit conductor pattern from regions of unused conductor on the printed circuit.

4. (Previously presented) A method according to claim 1 wherein the printed circuit conductor pattern includes conductor regions less than about 30 microns wide.

5. (Previously presented) A method according to claim 1 wherein the printed circuit conductor pattern includes conductor regions spaced by less than about 30 microns.

6. (Previously presented) A method according to claim 1 wherein the etch band is less than about 30 microns wide.

7. (Previously presented) A mask for use in producing a resist pattern for etching of a printed circuit, the mask being produced by the method of any one of the preceding claims.

Claims 8-13. (Canceled).

14. (Currently amended) A method of producing a printed circuit comprising a pattern of conductor elements, the method comprising the steps of: defining on a printed circuit substrate a pattern of resist to leave exposed regions of conductor to be etched away, the exposed regions comprising areas of constant width delineating the conductor elements and etching away said exposed regions of conductor.

15. (Original) A method according to claim 14 wherein the conductor elements include elements less than about 30 microns wide.

16. (Previously presented) A method according to claim 14 wherein the pattern includes conductor elements spaced by less than about 30 microns.

17. (Previously presented) A method according to claim 14 wherein the regions of constant width are of substantially the same width as the narrowest element or narrowest separation between elements in the printed circuit.

Claims 18-19. (Canceled).